

SOT1078-1

plastic very thin fine-pitch ball grid array package; 144 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA144
Package type industry code	VFBGA144
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	---
Mounting method type	S (surface mount)
Issue date	7-4-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.4	-	5.5	5.6	mm
E	package width		5.4	-	5.5	5.6	mm
A	seated height		0.8	-	0.9	1	mm
A ₂	package height		0.65	-	0.7	0.75	mm
n ₂	actual quantity of termination		-	-	144	-	



2. Package outline

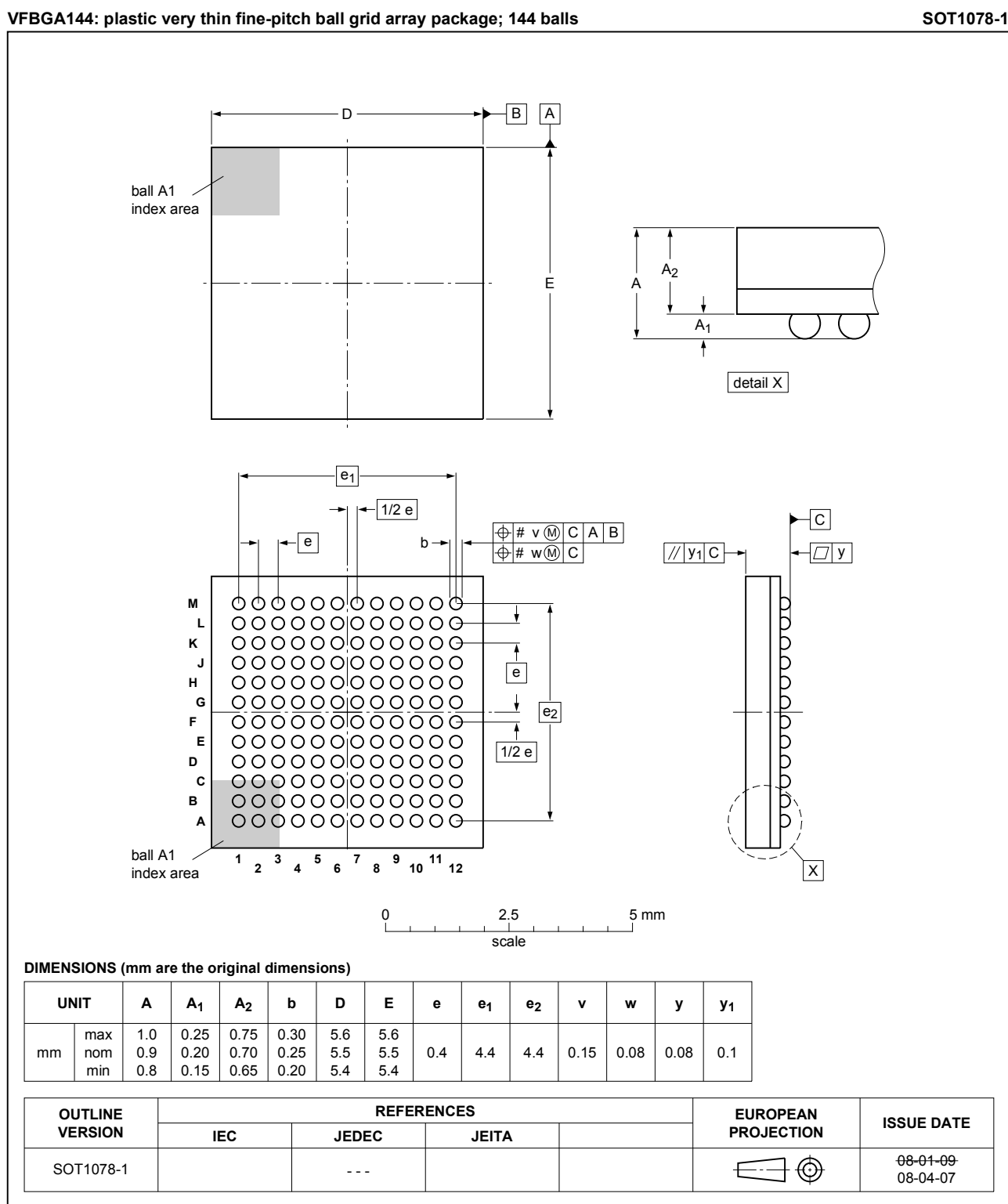


Fig. 1. Package outline VFBGA144 (SOT1078-1)

3. Soldering

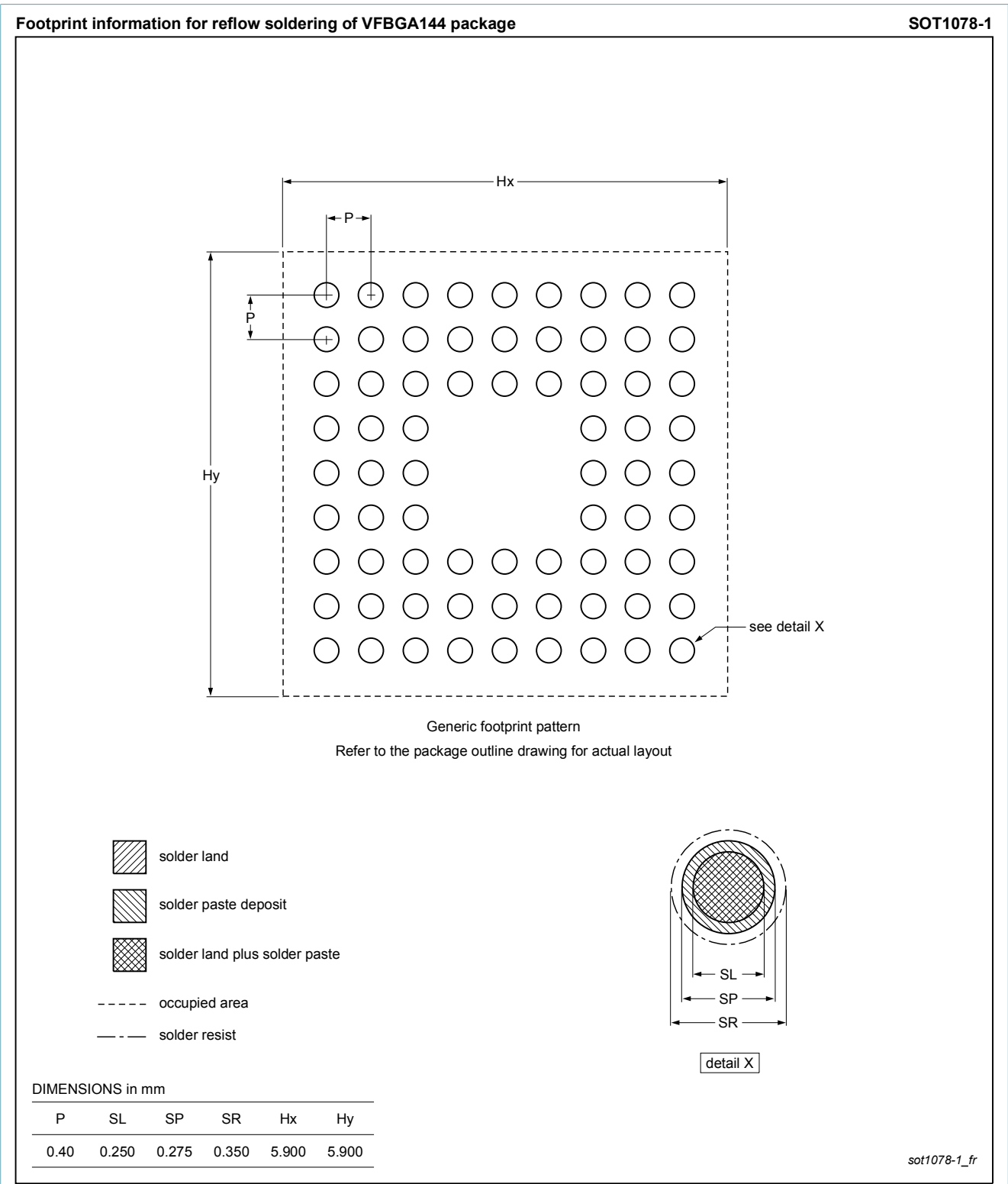


Fig. 2. Reflow soldering footprint for VFBGA144 (SOT1078-1)

4. Legal information

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5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 4

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